LEC-iMX6

SMARC[®] Short Size Module with Freescale i.MX6 Solo, DualLite, Dual or Quad Processor

SMARC



STANDARDIZATION GROUP FOR

EMBEDDED TECHNOLOGIES

Features

- Freescale SoC i.MX6 ARM Cortex A9 Solo, DualLite, Dual or Quad processor
- Integrated 2D/3D graphics processors, 3D 1080p video processing, power management
- Onboard DDR3L/1067 system memory from 512 MB to 2 GB
- Supports up to 64 GB eMMC, 1x SD/MMC, 1x SATA 3Gb/s
- Extreme Rugged ™ operating temperature: -40°C to +85°C

SMARC *LEC = Low Energy Computer-on-Module

Specifications

Core System	
CPU	Freescale i.MX6 Solo, DualLite, Dual or Quad processor
	i.MX6 Quad, 4 cores, 800 MHz, 1 MB L2 cache, 3 displays, 1x SATA
	i.MX6 Dual, 2 cores, 800 MHz, 1 MB L2 cache, 3 displays, 1x SATA
	i.MX6 DualLite, 2 cores, 800 MHz, 512 kB L2 cache, 1 display, no SATA
	i.MX6 Solo, 1 core, 800 MHz, 512 kB L2 cache, 1 display, no SATA
Memory	Onboard DDR3L-1066 system memory from 512 MB to 2 GB
Boot Loader	U-Boot boot loader
L2 Cache	From 512 kB to 1 MB
SEMA Board Controller	Supports: Voltage/Current monitoring, Logistics and Forensic information, Flat Panel Control, General Purpose I ² C, Failsafe SPI Flash, Watchdog Timer
Debug Headers	JTAG debug interface on test-points

Graphics

Parallel LCD 24-bit
LVDS single channel 24-bit
HDMI 1.4a

Video

High-performance video processing unit (VPU), supports SD and HD-level video decoders and SD-level encoders as a multi-standard video codec engine, as well as several important video processing functions, such as rotation and mirroring

Audio	
Audio Codec	Located on carrier
Interface	S/PDIF
Ethernet	

Interface

10/100/1000 GbE

I/O Interfaces	
USB	2x USB 2.0 host, 1x USB OTG
SATA	1x SATA 3Gb/s
Serial	4x UART
Flash Memory	Up to 64 GB eMMC (custom option)
GPIO	12x GPIO with interrupt
PCle	1x PCle x1
SDIO	1x SDIO
SPI	2x SPI
I ² C	3x I ² C
I2S	1x I ² S
S/PDIF	1x S/PDIF
WDT	1x WDT
CAN	2x CAN
Management	Battery and System Management

Camera

1

Serial	MIPI CSI camera, 2 lanes
Parallel	PCAM, 10-bit

Mechanical and Environmental

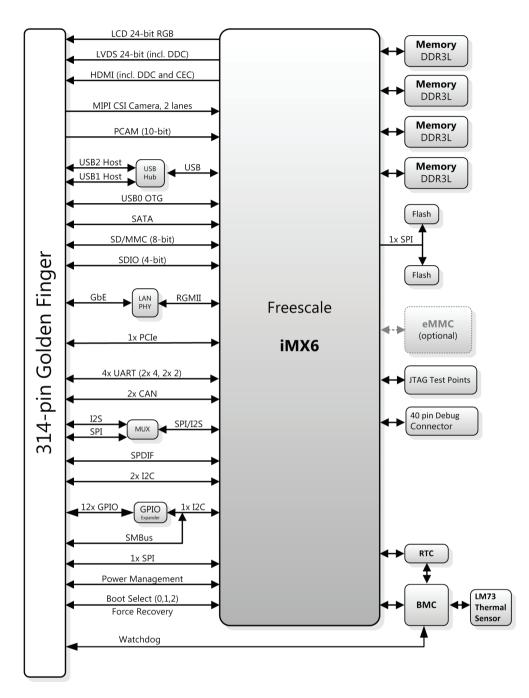
Form Factor	SMARC Specification v1.0
Dimensions	SMARC short size module, 82 mm x 50 mm
Operating Temperature	Standard: 0°C to +60°C
	Extreme Rugged™: -40°C to +85°C
Humidity	5-90% RH non-condensing
	5-95% RH storage (and operating with conformal coating)
Shock and Vibration	IEC 60068-2-64 and IEC-60068-2-27 MIL-STD-202F, Method 213B, Table 213-I, Condition A and Method 214A, Table 214-I, Condition D
HALT	Thermal Stress, Vibration Stress, Thermal Shock and Combined Test

Operating Systems

Standard Support On request

Windows Embedded Compact 7, Linux Android, VxWorks, QNX

Functional Diagram



Ordering Information

Modules		
Model Number	Description/Configuration	
LEC-iMX64-2G-8G-ER	SMARC [*] Short Module with Freescale i.MX6, Quad, 2 GB RAM, 8 GB eMMC, -40°C to +85°C	
LEC-iMX62-2G-8G-ER	SMARC [°] Short Module with Freescale i.MX6, Dual, 2 GB RAM, 8 GB eMMC, -40°C to +85°C	
LEC-iMX62-1G-4G-ER	SMARC [*] Short Module with Freescale i.MX6, Dual, 1 GB RAM, 4 GB eMMC, -40°C to +85°C	

LEC-iMX62L-2G-8G-ER	SMARC [*] Short Module with Freescale i.MX6, DualLite, 2 GB RAM, 8 GB eMMC, -40°C to +85°C
LEC-iMX61-1G-8G-ER	SMARC [*] Short Module with Freescale i.MX6, Solo, 1 GB RAM, 8 GB eMMC, -40°C to +85°C
LEC-iMX6-HS	Heatspreader for LEC-iMX6

ADLINK